

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S208	4	("20020017718" "6313529").PN. OR ("6635962").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S207	329	S206 and lead near1 frame and (solder near2 ball bump c4 flip)	USPAT	OR	ON	2008/01/19 19:45
S206	2255	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/19 19:45
S205	202	(plur\$5 multi) near2 (film layer laminat\$3) with frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S204	51	(plur\$5 multi) near2 (film layer laminat\$3) near2 frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S203	667	(plur\$5 multi) near2 (film layer laminat\$3) near2 frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S202	2258	(plur\$5 multi) near2 (film layer laminat\$3) with frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S201	0	("(plur\$5multi)near2(film layer laminat \$3)withframeand(ICsemiconductor si liconintegratedadjcircuit chip die wafer)").PN.	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/19 19:45
S200	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S199	1	"6734044".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S198	12	S196 and (solder adj contact solder near ball bump c4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S197	151	S196 not S191	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S196	156	multi\$3layer near2 lead adj frame	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45

EAST Search History

S19 5	4	("3784948" "3925801" "4627151").PN. OR ("6255141"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S19 4	2	"6255141".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S19 3	235	S190 or S191	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S19 2	60	S190 and S191	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S19 1	156	S189 and 257/67\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S19 0	139	S189 and 257/66\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S18 9	1561	laminat\$3 with lead adj frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S18 8	142	("3784883" "4168507" "4541035" "4577214" "4595945" "4608592" "4639760" "4675717" "4680613" "4705917").PN. OR ("4891687"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S18 7	11	("3597834" "3848077" "4113981" "4925024" "5025114" "5180888" "5183969" "5262226").PN. OR ("5399809").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S18 6	55	S185 not S181	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45

EAST Search History

S18 5	80	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium it tungsten w gold au) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S18 4	27	S182 not S181	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S18 3	37	S182 not "44"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S18 2	52	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S18 1	25	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) same lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S18 0	41	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S17 9	95	S178 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S17 8	231	S173 and "257"/\$.ccls.	USPAT	OR	ON	2008/01/19 19:45
S17 7	95	S174 and "257"/\$.ccls.	USPAT	OR	ON	2008/01/19 19:45
S17 6	144	S174 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45

EAST Search History

S17 5	2557	(IC chip integrated near2 circuit die semiconductor) near S171 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S17 4	220	S173 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S17 3	2557	(IC chip integrated near2 circuit die semiconductor) near S171 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S17 2	2	S171 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S17 1	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S17 0	3	"5196725".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S16 9	2	"5229647".pn.	USPAT; DERWENT	OR	ON	2008/01/19 19:45
S16 8	3	"5196725".pn.	USPAT; DERWENT	OR	ON	2008/01/19 19:45
S16 7	2	"5191725".pn.	USPAT; DERWENT	OR	ON	2008/01/19 19:45
S16 6	1	1992-386699.NRAN.	DERWENT	OR	ON	2008/01/19 19:45
S16 5	9	(US-5777265-\$ or US-5734198-\$ or US-5399809-\$ or US-5864173-\$ or US-5214845-\$ or US-4891687-\$ or US-5389816-\$).did. or (US-5777265-\$ or JP-04286148-\$). did.	USPAT; DERWENT	OR	ON	2008/01/19 19:45
S16 4	36	("4445271" "4835120" "4891687" "5032895" "5053921" "5089878" "5089881").PN. OR ("5220195"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45

EAST Search History

S16 3	6	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S16 2	9	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN. OR ("5389816"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S16 1	26	(Multi near2 layer with lead near2 frame).ti. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S16 0	25	("4320438" "4839717" "4879588" "4891687" "4972253" "4980034" "5008734" "5012386" "5158912" "5235209" "5235211" "5258575" "5264729" "5272590" "5311057" "5331511").PN. OR ("5777265"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S15 9	11	("5,196,725", "5,237,202", "5,399, 809", "5,734,198" "5,777,265").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S15 8	465	S157 and (multi near2 layer multilayer laminate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S15 7	4556	(257/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/19 19:45
S15 6	3	("6081031" "6555899" "6677672").PN. OR ("6734044"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S15 5	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S15 4	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S15 3	1	"6734044".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S15 2	12	S150 and (solder adj contact solder near ball bump c4)	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45

EAST Search History

S15 1	151	S150 not S145	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S15 0	156	multi\$3layer near2 lead adj frame	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S14 9	4	("3784948" "3925801" "4627151").PN. OR ("6255141"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S14 8	2	"6255141".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S14 7	235	S144 or S145	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S14 6	60	S144 and S145	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S14 5	156	S143 and 257/67\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S14 4	139	S143 and 257/66\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S14 3	1561	laminat\$3 with lead adj frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S14 2	142	("3784883" "4168507" "4541035" "4577214" "4595945" "4608592" "4639760" "4675717" "4680613" "4705917").PN. OR ("4891687"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S14 1	11	("3597834" "3848077" "4113981" "4925024" "5025114" "5180888" "5183969" "5262226").PN. OR ("5399809").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45

EAST Search History

S14 0	55	S139 not S135	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S13 9	80	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium it tungsten w gold au) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S13 8	27	S136 not S135	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S13 7	37	S136 not "44"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S13 6	52	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S13 5	25	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) same lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S13 4	41	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S13 3	95	S132 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S13 2	231	S127 and "257"/\$.ccls.	USPAT	OR	ON	2008/01/19 19:45
S13 1	95	S129 and "257"/\$.ccls.	USPAT	OR	ON	2008/01/19 19:45

EAST Search History

S13 0	144	S129 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S12 9	220	S127 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S12 8	2	S126 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S12 7	2557	(IC chip integrated near2 circuit die semiconductor) near S126 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S12 6	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S12 5	3	"5196725".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S12 4	2	"5229647".pn.	USPAT; DERWENT	OR	ON	2008/01/19 19:45
S12 3	3	"5196725".pn.	USPAT; DERWENT	OR	ON	2008/01/19 19:45
S12 2	2	"5191725".pn.	USPAT; DERWENT	OR	ON	2008/01/19 19:45
S12 1	1	1992-386699.NRAN.	DERWENT	OR	ON	2008/01/19 19:45
S12 0	9	(US-5777265-\$ or US-5734198-\$ or US-5399809-\$ or US-5864173-\$ or US-5214845-\$ or US-4891687-\$ or US-5389816-\$).did. or (US-5777265-\$ or JP-04286148-\$).did.	USPAT; DERWENT	OR	ON	2008/01/19 19:45
S11 9	36	("4445271" "4835120" "4891687" "5032895" "5053921" "5089878" "5089881").PN. OR ("5220195").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45

EAST Search History

S11 8	6	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S11 7	9	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN. OR ("5389816"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S11 6	26	(Multi near2 layer with lead near2 frame).ti. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S11 5	25	("4320438" "4839717" "4879588" "4891687" "4972253" "4980034" "5008734" "5012386" "5158912" "5235209" "5235211" "5258575" "5264729" "5272590" "5311057" "5331511").PN. OR ("5777265"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S11 4	11	("5,196,725", "5,237,202", "5,399, 809", "5,734,198" "5,777,265").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S11 3	465	S112 and (multi near2 layer multilayer laminate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S11 2	4556	(257/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/19 19:45
S11 1	3	("6081031" "6555899" "6677672").PN. OR ("6734044"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 19:45
S11 0	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/19 19:45
S10 9	18	("5578525" "5580795" "5909058" "6188127" "6204562" "6287892" "6324067" "6350954").PN. OR ("6548330").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 18:45
S10 8	12	("3908185" "4866571" "5057376" "5404273" "5689091" "5801446" "5847936" "5936305" "6011692").PN. OR ("6350954"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 18:40

EAST Search History

S10 7	163	S106 and cavity	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 18:35
S10 6	563	S104 and S105	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 18:34
S10 5	639	(lead near1 frame or leadframe) with (multilayer\$3 or multi near1 layer\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 18:34
S10 4	20073	(lead near1 frame or leadframe). bstx.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 18:33
S10 3	17	("20020020907" "20020031856" "5243498" "5629563" "6143981" "6236109" "6284570" "6369454" "6458617" "6507098").PN. OR ("6677672").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 18:31
S10 2	3	("6081031" "6555899" "6677672").PN. OR ("6734044"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 18:30
S10 1	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 18:30
S10 0	3	("6081031" "6555899" "6677672").PN. OR ("6734044"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/19 18:28
S99	4	("20020017718" "6313529").PN. OR ("6635962").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/15 17:33
S98	292	S97 and lead near1 frame and (solder near2 ball bump c4 flip)	USPAT	OR	ON	2006/11/15 17:29
S97	1904	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/15 17:29
S1	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/15 17:28
S95	50	(plur\$5 multi) near2 (film layer laminat\$3) near2 frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/15 09:00
S96	188	(plur\$5 multi) near2 (film layer laminat\$3) with frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/15 08:59

EAST Search History

S94	598	(plur\$5 multi) near2 (film layer laminat\$3) near2 frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/15 08:59
S93	1987	(plur\$5 multi) near2 (film layer laminat\$3) with frame and (IC semiconductor silicon integrated adj circuit chip die wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/15 08:59
S92	0	("(plur\$5multi)near2(filmlayerlaminat\$3)withframeand(ICsemiconductorsiliconintegratedadjcircuitchipdiewafer)").PN.	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/15 08:57
S91	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S90	1	"6734044".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S89	8	S87 and (solder adj contact solder near ball bump c4)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S88	132	S87 not S82	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S87	137	multi\$3layer near2 lead adj frame	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S86	3	("3784948" "3925801" "4627151").PN. OR ("6255141").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S85	2	"6255141".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S84	204	S81 or S82	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S83	55	S81 and S82	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47

EAST Search History

S82	138	S80 and 257/67\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S81	121	S80 and 257/66\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S80	1317	laminat\$3 with lead adj frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S79	138	("3784883" "4168507" "4541035" "4577214" "4595945" "4608592" "4639760" "4675717" "4680613" "4705917").PN. OR ("4891687"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S78	9	("3597834" "3848077" "4113981" "4925024" "5025114" "5180888" "5183969" "5262226").PN. OR ("5399809").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S77	47	S76 not S72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S76	71	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium it tungsten w gold au) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S75	25	S73 not S72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S74	34	S73 not "44"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47

EAST Search History

S73	49	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S72	24	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) same lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S71	38	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S70	87	S69 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S69	205	S64 and "257"/\$.ccls.	USPAT	OR	ON	2005/12/12 21:47
S68	87	S65 and "257"/\$.ccls.	USPAT	OR	ON	2005/12/12 21:47
S67	126	S65 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S66	2255	(IC chip integrated near2 circuit die semiconductor) near S62 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S65	197	S64 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S64	2255	(IC chip integrated near2 circuit die semiconductor) near S62 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47

EAST Search History

S63	2	S62 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S62	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S61	3	"5196725".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S60	2	"5229647".pn.	USPAT; DERWENT	OR	ON	2005/12/12 21:47
S59	3	"5196725".pn.	USPAT; DERWENT	OR	ON	2005/12/12 21:47
S58	2	"5191725".pn.	USPAT; DERWENT	OR	ON	2005/12/12 21:47
S57	1	1992-386699.NRAN.	DERWENT	OR	ON	2005/12/12 21:47
S56	9	(US-5777265-\$ or US-5734198-\$ or US-5399809-\$ or US-5864173-\$ or US-5214845-\$ or US-4891687-\$ or US-5389816-\$).did. or (US-5777265-\$ or JP-04286148-\$). did.	USPAT; DERWENT	OR	ON	2005/12/12 21:47
S55	35	("4445271" "4835120" "4891687" "5032895" "5053921" "5089878" "5089881").PN. OR ("5220195"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S54	6	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S53	9	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN. OR ("5389816"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S52	25	(Multi near2 layer with lead near2 frame).ti. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S51	22	("4320438" "4839717" "4879588" "4891687" "4972253" "4980034" "5008734" "5012386" "5158912" "5235209" "5235211" "5258575" "5264729" "5272590" "5311057" "5331511").PN. OR ("5777265"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47

EAST Search History

S50	11	("5,196,725", "5,237,202", "5,399,809", "5,734,198" "5,777,265").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S49	385	S48 and (multi near2 layer multilayer laminate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S48	3987	(257/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:47
S47	3	("6081031" "6555899" "6677672").PN. OR ("6734044").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
S46	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
S45	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 16:39
S44	1	"6734044".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 16:38
S43	8	S41 and (solder adj contact solder near ball bump c4)	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 16:38
S42	130	S41 not S36	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 16:21
S41	135	multi\$3layer near2 lead adj frame	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 16:21
S40	3	("3784948" "3925801" "4627151").PN. OR ("6255141").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 16:20
S39	2	"6255141".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/23 16:05

EAST Search History

S38	200	S35 or S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/23 16:05
S37	53	S35 and S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/23 16:02
S36	134	S34 and 257/67\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/23 16:02
S35	119	S34 and 257/66\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/23 16:02
S34	1278	laminat\$3 with lead adj frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/23 16:01
S33	136	("3784883" "4168507" "4541035" "4577214" "4595945" "4608592" "4639760" "4675717" "4680613" "4705917").PN. OR ("4891687"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 16:01
S32	9	("3597834" "3848077" "4113981" "4925024" "5025114" "5180888" "5183969" "5262226").PN. OR ("5399809").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/23 15:58
S31	41	S30 not S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 17:37
S30	65	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium it tungsten w gold au) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:43

EAST Search History

S27	44	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:43
S29	20	S27 not S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:41
S28	32	S27 not "44"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:41
S26	24	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) same lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:41
S25	37	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:39
S18	2136	(IC chip integrated near2 circuit die semiconductor) near S17 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:36
S24	83	S23 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:35
S20	187	S18 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:35
S23	194	S18 and "257"/\$.ccls.	USPAT	OR	ON	2005/02/03 16:34
S22	83	S20 and "257"/\$.ccls.	USPAT	OR	ON	2005/02/03 16:34

EAST Search History

S21	120	S20 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:14
S19	2	S17 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:13
S17	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:10
S16	3	"5196725".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 16:06
S15	2	"5229647".pn.	USPAT; DERWENT	OR	ON	2005/02/03 13:47
S14	3	"5196725".pn.	USPAT; DERWENT	OR	ON	2005/02/03 13:47
S13	2	"5191725".pn.	USPAT; DERWENT	OR	ON	2005/02/03 11:13
S11	9	(US-5777265-\$ or US-5734198-\$ or US-5399809-\$ or US-5864173-\$ or US-5214845-\$ or US-4891687-\$ or US-5389816-\$):did. or (US-5777265-\$ or JP-04286148-\$). did.	USPAT; DERWENT	OR	ON	2005/02/03 11:13
S12	1	1992-386699.NRAN.	DERWENT	OR	ON	2005/02/03 11:12
S10	35	("4445271" "4835120" "4891687" "5032895" "5053921" "5089878" "5089881").PN. OR ("5220195"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/03 10:49
S9	6	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/03 10:48
S8	9	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN. OR ("5389816"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/03 10:23
S7	25	(Multi near2 layer with lead near2 frame).ti. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/03 10:20

EAST Search History

S6	22	("4320438" "4839717" "4879588" "4891687" "4972253" "4980034" "5008734" "5012386" "5158912" "5235209" "5235211" "5258575" "5264729" "5272590" "5311057" "5331511").PN. OR ("5777265"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/03 10:18
S5	11	("5,196,725", "5,237,202", "5,399, 809", "5,734,198" "5,777,265").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 10:15
S4	349	S3 and (multi near2 layer multilayer laminate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 10:14
S3	3748	(257/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/03 10:12
S2	3	("6081031" "6555899" "6677672").PN. OR ("6734044"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/02/03 10:12